

Section

MV Semi-conductor

Application

Field

Laboratory



PRODUCT BENEFITS

No silicon needed
 Fine tuning of the blade with a 'click' for each 1/10 mm
 Very smooth finish over the insulation
 Achievement of a clean and straight semicon cutback

TOOL CAPACITY

Diameter	18 - 60 mm 0,709 - 2,362 inch
Thickness capacity	1,8 mm / 0,071 in
Angle of the chamfer on the semiconductor	13 °
Remaining length of the semiconductor	With MVS stop

TOOL DIMENSIONS

Length	235 mm
Width	125 mm
Height	90 mm
Weight without box	0,9 Kg
Packaging	Box

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Tool to remove bonded semiconductor with chamfer on the semiconductor cutback and stop for MV cable

TO DO WHAT

The CWB/18-60 enables the user to easily remove the bonded semi-conductor without silicon and with a chamfer on the semicon cutback.

The MVS sits on the cable to stop the CWB/18-60-MVS with a large contact surface.



Spare part

LCWB-FEP - Spare blade for bonded semiconductor with chamfer 13°

Associated tool

GRI-RTE - Scraper for residues of bonded semiconductor screen with protective case

PG3HTA/2530 - Pliers for MV cables outer sheath

BRMRD1E - Tool to remove insulation



Part Number	Diameter	Tool capacity			Dimensions			Packaging
		Thickness capacity	Angle of the chamfer on the semiconductor	Remaining length of the semiconductor	Length	Width	Height	
CWB/18-60	18 - 60 mm 0,709 - 2,362 in	1,1 mm / 0,043 in	8°	25-30-40 mm / 0,984-1,181-1,575 in	235 mm 9,252 in	125 mm 4,921 in	90 mm 3,543 in	box
CWB/18-60-FEP	18 - 60 mm 0,709 - 2,362 in	1,8 mm / 0,071 in	13°	25-30-40 mm / 0,984-1,181-1,575 in	235 mm 9,252 in	125 mm 4,921 in	90 mm 3,543 in	box
CWB/18-60-MVS	18 - 60 mm 0,709 - 2,362 in	1,8 mm / 0,071 in	13 °	With MVS stop	235 mm 9,252 in	125 mm 4,921 in	90 mm 3,543 in	box